



Title of Change:	Copper wire conversion for LV8548MC and LV8549MC												
Proposed first ship date:	21 June 2018												
Contact information:	Contact your local ON Semiconductor Sales Office or <Tsutomu.Shimazaki@onsemi.com>												
Samples:	Contact your local ON Semiconductor Sales Office or <Tsutomu.Shimazaki@onsemi.com>												
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Satoru.Fujinuma@onsemi.com>												
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.												
Change Part Identification:	Affected products will be identified with date code.												
Change category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____												
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____												
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines	External Foundry/Subcon Sites: None											
Description and Purpose:													
This is a Final Process Change Notification announces the following change on LV8548MC-AH and LV8549MC-AH:													
	<table border="1"> <thead> <tr> <th rowspan="2">Material to be changed</th> <th>Before Change</th> <th>After Change</th> </tr> <tr> <th>Description</th> <th>Description</th> </tr> </thead> <tbody> <tr> <td>Wire</td> <td>Gold wire</td> <td>Copper wire</td> </tr> <tr> <td>Mold resin</td> <td>G600</td> <td>G700LS</td> </tr> </tbody> </table>		Material to be changed	Before Change	After Change	Description	Description	Wire	Gold wire	Copper wire	Mold resin	G600	G700LS
Material to be changed	Before Change	After Change											
	Description	Description											
Wire	Gold wire	Copper wire											
Mold resin	G600	G700LS											



Reliability Data Summary:

QV DEVICE NAME : LV8548MC

PACKAGE : SOIC10

Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Tj=Tjmax, Vcc=Operatingmax	1000 hrs	0/22
THB*	EIAJ ED-4701/100	85°C, 85% RH, Vcc=recommended	1000 hrs	0/22
TC*	EIAJ ED-4701/100	Ta= -65°C to +150°C	100 cyc	0/22
AC*	EIAJ ED-4701-3	Ta=121°C ,RH=100% ,205kPa	50 hrs	0/22
HTSL	EIAJ ED-4701/200	Ta= 150°C	1000 hrs	0/22
RSH	EIAJ ED-4701/300	Ta = 255°C , 10 sec (peak 260°C)	2times	0/22

Notes:

The test items with * mark are put into operation after the reflow soldering (at 255°C for 10seconds)

Electrical Characteristic Summary:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LV8548MC-AH	LV8548MC-AH
LV8549MC-AH	



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
LV8548MC-AH		LV8548MC-AH
LV8549MC-AH		LV8548MC-AH